



SOT1061

DFN2020-3: plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body 2 x 2 x 0.65 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN2020-3
Package type industry code	DFN2020-3
Package style descriptive code	HUSON (thermal enhanced ultra thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	7-10-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	[tbd]	-	0.65	0.65	mm
n ₂	actual quantity of termination	-	-	3	-	



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2. Package outline

HUSON3: plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body 2 x 2 x 0.65 mm

SOT1061

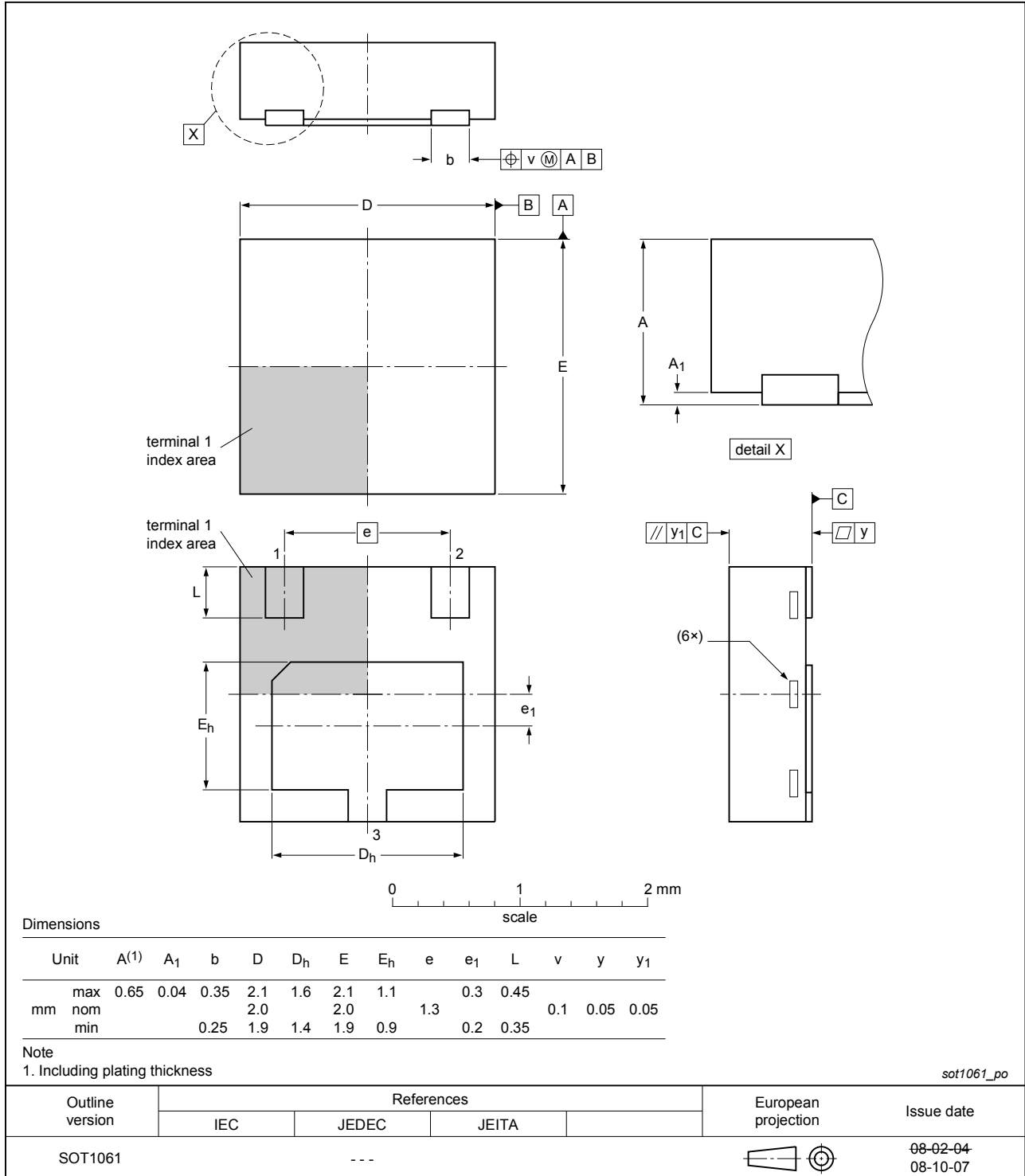


Fig. 1. Package outline DFN2020-3 (SOT1061)

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3. Soldering

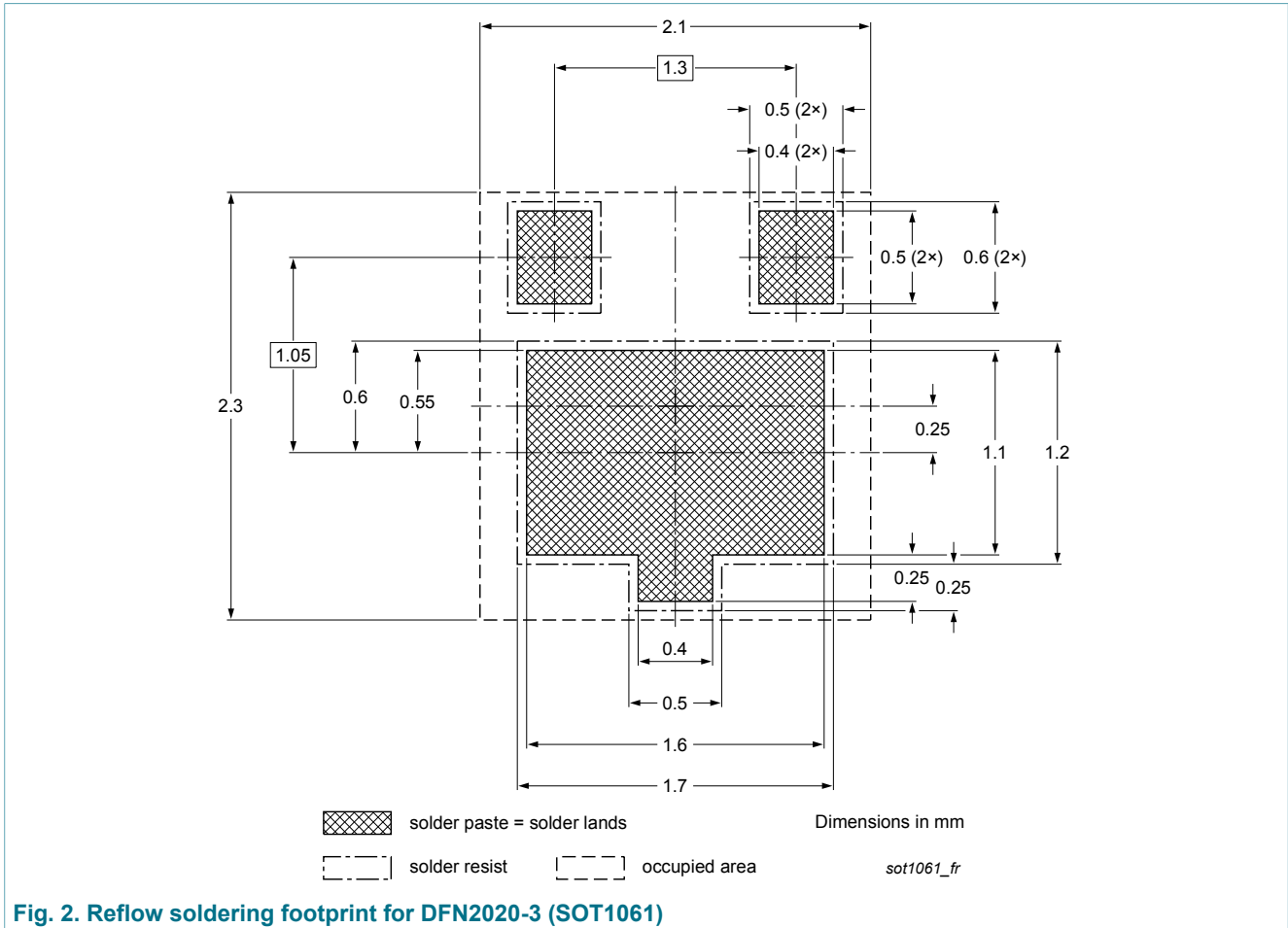


Fig. 2. Reflow soldering footprint for DFN2020-3 (SOT1061)

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4. Legal information

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